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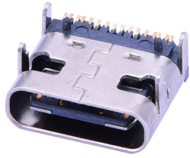
CARD SOCKETS

Operation:贴片卧式& 2.0Type-C 连接器/16PIN+4DIP 结构

LTEM NO.:MC-311D-M2 (M2/M3:2/3 MOLDING)

(7.35L×9.00W×4.35H & DUL SMT LOW PCB TYPE)

C-Universal Serial Bus Connectors



Technical parameter

PROJECT \ LEVEL		A[better product]	B[average product]
Electrical Properties	Contact Rating	5A, 12V DC	
	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD：100MΩ min.300V DC
	Withstand Voltage	350V AC for 1 minute	250 V AC for 1 minut
Durable Performance	There No Load	10,000 Cycles	8,500 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
Sterage temp.		-25℃～+75℃(Operating Temp:)	

外焊 SMT+DIP

侧向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

環保材质 RoHS

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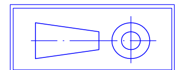
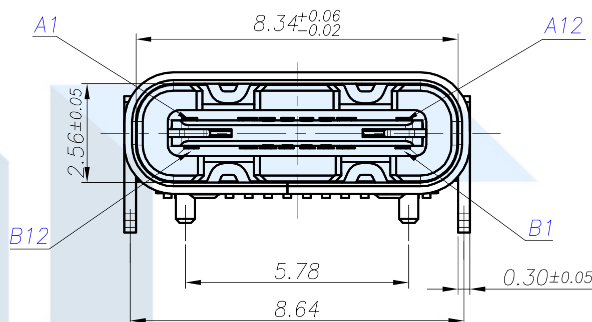
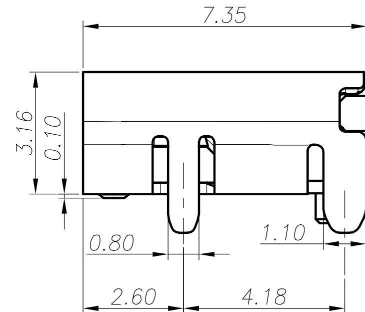
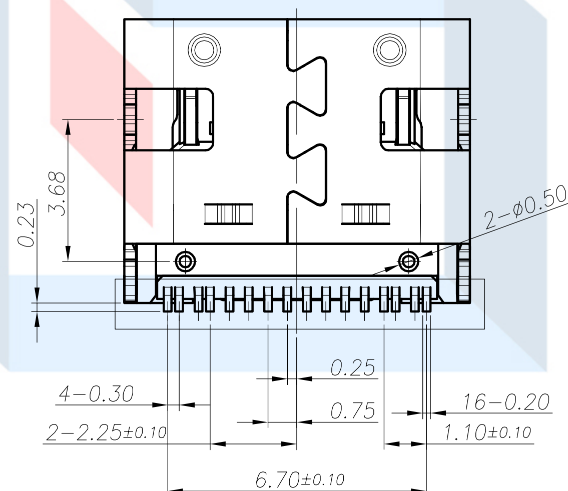
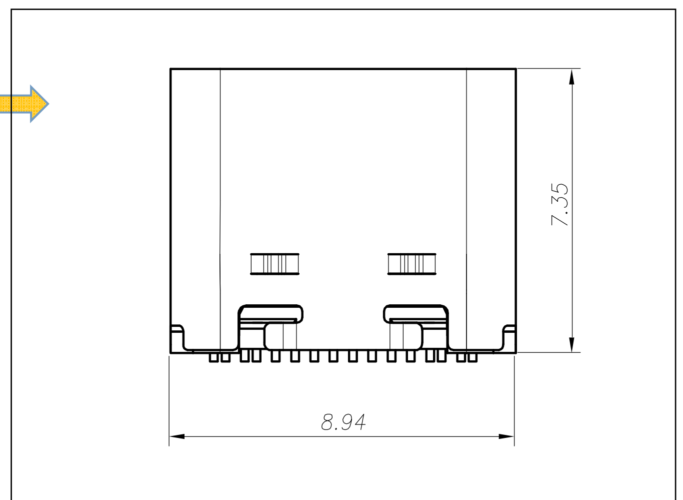
Unit:mm

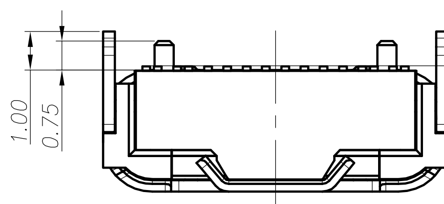


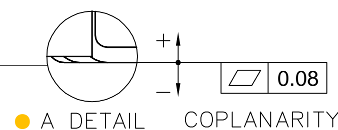


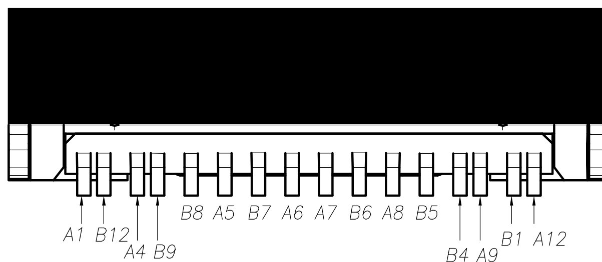












SPECIFED TOLERANCES

UNLESS OTHERWISE

DECIMALS	ANGLES
X.X :±0.20	X.X :±2°
X.XX :±0.10	X.XX :±1.5°
X.XXX :±0.05	

手焊接时

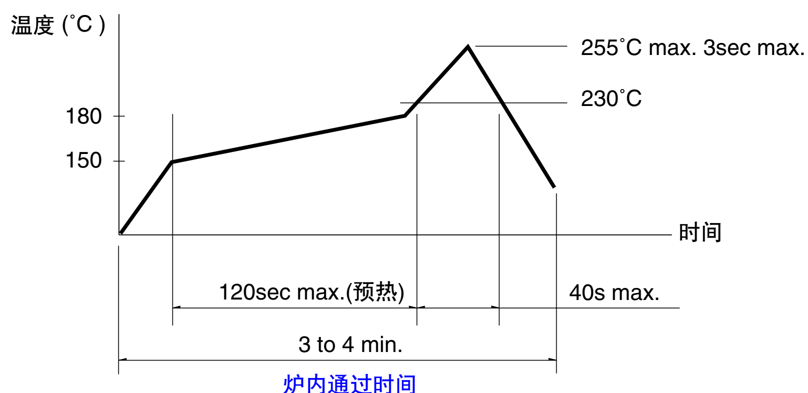
项 目	条 件
焊接温度	350℃max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

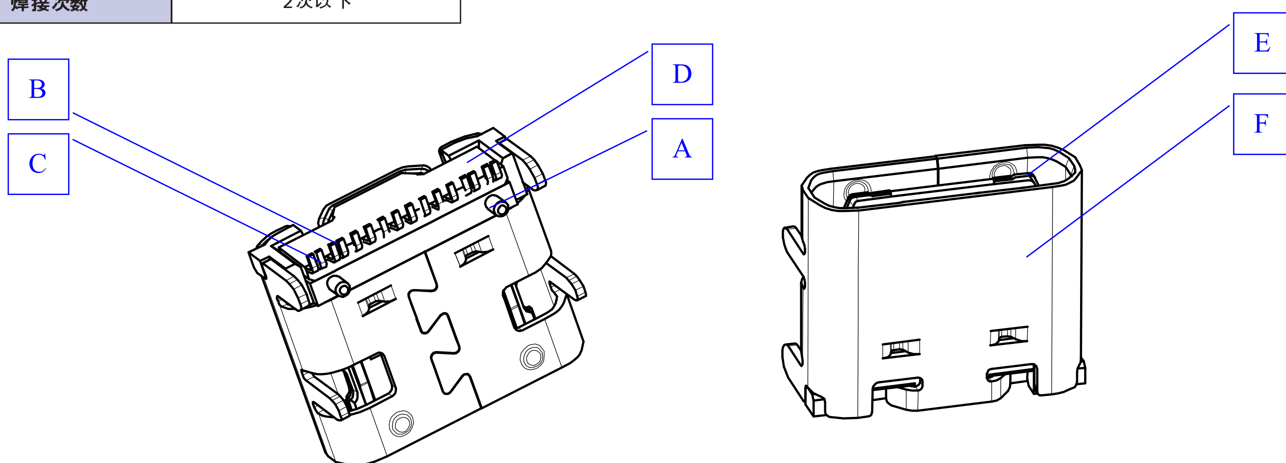
自动浸焊时

项 目	条 件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100℃ max.
预热温度时间	60s max.
焊接温度	255℃ max.
焊接浸渍时间	5s max.
焊接次数	2次以下

回流焊时

1. 加热方式　以远红外线加热的上下加热方式。
2. 温度测量方式　使用ϕ0.1～ϕ0.2的CA(K)或CC(T)测量。
3. 温度分布　位置在焊接连接部(铜箔面)测量。

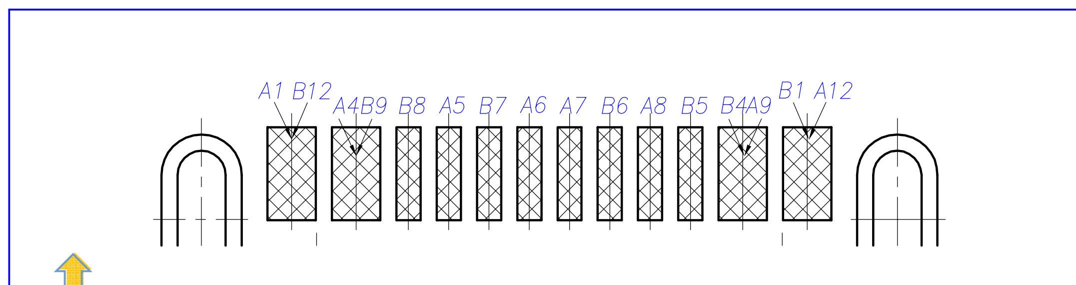


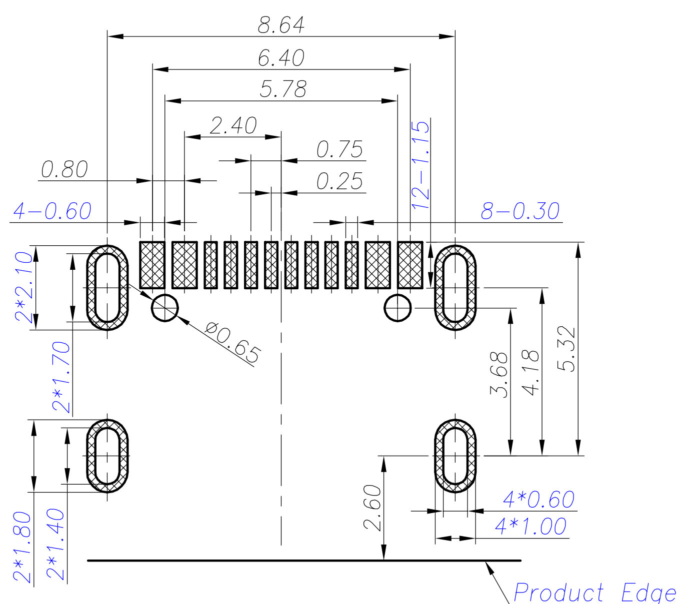


Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	HOUSING	1	LCP(glass fiber filled)BK
② B	CONTACT	10/F1+W10	COPPER ALLOY /Au NI Plated(t=0.12mm)
③ C	CONTACT	4/F1+W10	COPPER ALLOY /Au NI Plated(t=0.12mm)
④ D	MD	1	HIGH TEMPERATURE PLASTIC(Black)
⑤ E	SHIELDING PLATE	1/S1-N5	STAINLESS STEEL(t=0.30mm)
⑥ F	SHIELD	1/S1+N5	STAINLESS STEEL(t=0.30mm)

CIRCUIT BOARD SIZE (Vertical view)

Operating Force	Inward	5.0～8.0N.(1N.=100gram-force)	Solder-ability (Max.)	
	Exiting	5.0～8.0N.(1N.=100gram-force)	IR Reflow:255℃,5sec.	Manual:350℃,3sec.





PIN ASSIGNMENTS

PIN	Signal NAME	Description		PIN	Signal NAME	Description
A 1	GND	Ground return		B12	GND	
A 4	V BUS	Bus Power		B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel		B 8	SBU2	Sideband Use(SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1		B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1		B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use(SBU)		B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power		B 4	V BUS	Bus Power
A12	GND	Ground return		B 1	GND	Ground return

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